Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **BAL COMP**
2. **INPUT-**
3. **INPUT+**
4. **V-**
5. **BAL**
6. **OUTPUT**
7. **V+**
8. **COMP**

**.047”**

**1**

**2**

**3**

**8 7 6**

**4 5**

**MASK**

**REF**

**.046”**

**Top Material: Al**

**Backside Material: Si**

**Bond Pad Size = .004 x .004”**

**Backside Potential: FLOAT**

**Mask Ref: 0452**

**APPROVED BY: DK DIE SIZE .046” X .047” DATE: 8/17/21**

**MFG: SILICON SUPPLIES THICKNESS .014” P/N: LM101A**

**DG 10.1.2**

#### Rev B, 7/1